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PCN# : P2A2A
Issue Date : Oct. 31, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

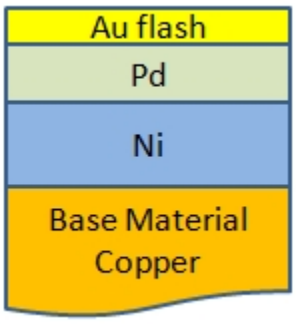
Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

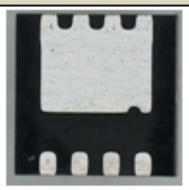
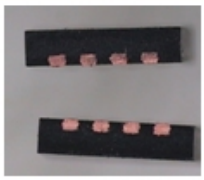
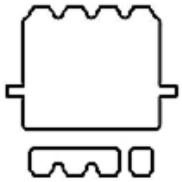
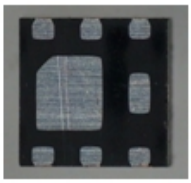
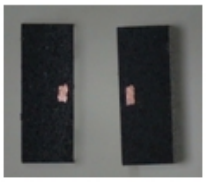
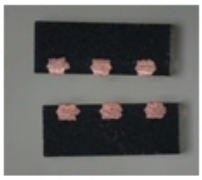
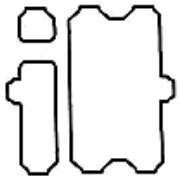
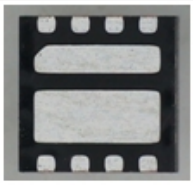
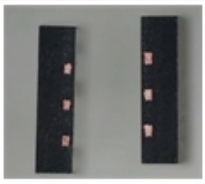
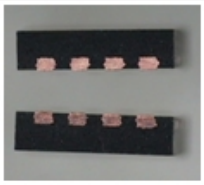
Expected First Shipment Date for Changed Product : Jan. 29, 2013

Expected First Date Code of Changed Product :1253

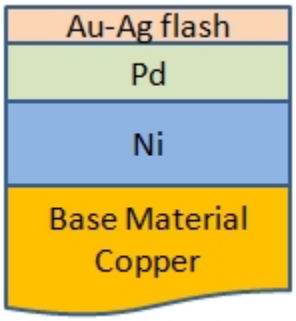
Description of Change (From) :
1) Standard leadframe with NiPdAu plating finish.



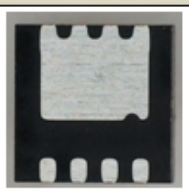
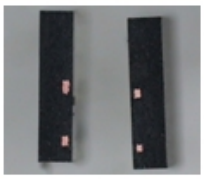
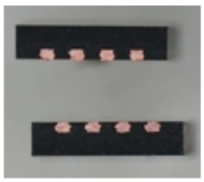
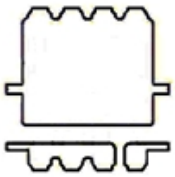
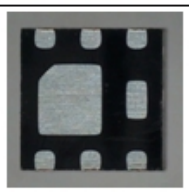
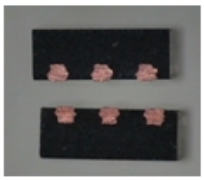
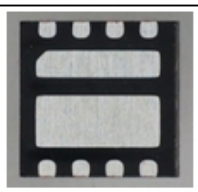
2) No tie bar connected to the corner leads of the package. Package outline view and diagram as shown in the table below.

Package	Bottom view	Side view (tie bar)	Side view (leads)	Leadframe Diagram
MLP 3.3x3.3				
MLP 2x2				
MLP 3x3				

Description of Change (To) :
1) Roughened leadframe with NiPdAuAg plating finish.



2) Added tie bar to the corner leads of the package. Package outline view and diagram as shown in the table below.

Package	Bottom view	Side view (tie bar)	Side view (leads)	Leadframe Diagram
MLP 3.3x3.3				
MLP 2x2				
MLP 3x3				

Reason for Change:
This conversion is to align with Fairchild Penang's consolidation to a similar leadframe process to better utilize equipment. The change will not affect the product electrical specification and solderability. The products incorporating this change may be shipped interchangeably with existing unchanged products.

Affected Product(s):

FDMA905P_F147		

Qualification Plan	Device	Package	Process	No. of Lots
Q20110610	FDMC8884_F126	MLDEUC08	PT4 N	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/154
MSL1	260C, 3 cycles	**J-STD_020**		0/22
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	**JESD22-A110**	96 hrs	0/77
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/77
Bond Pull	9.0g	**JESD22-C100**		0/5
Bond Shear	90g	**AEC-Q100-001**		0/5
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/5
Solderability CA	Condition C steam aging (8hrs), Condition A solder Dip (215 for 5 sec)	**JESD22-B102**		0/11
Solderability CB	Condition C steam aging (8hrs), Condition B solder Dip (245 for 5 sec)	**JESD22-B102**		0/11

Qualification Plan	Device	Package	Process	No. of Lots
Q20110610	FDMC6683	MLDEUC08	ST3 P	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/154
MSL1	260C, 3 cycles	**J-STD_020**		0/22
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	**JESD22-A110**	96 hrs	0/77
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/77
Bond Pull	9.0g	**JESD22-C100**		0/5
Bond Shear	90g	**AEC-Q100-001**		0/5
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/5
Solderability CA	Condition C steam aging (8hrs), Condition A solder Dip (215 for 5 sec)	**JESD22-B102**		0/11
Solderability CB	Condition C steam aging (8hrs), Condition B solder Dip (245 for 5 sec)	**JESD22-B102**		0/11

Qualification Plan	Device	Package	Process	No. of Lots
Q20110610	FDMA510PZ	MLDEBC06	ST3 PZ	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/154
MSL1	260C, 3 cycles	**J-STD_020**		0/22
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	**JESD22-A110**	96 hrs	0/77
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/77
Bond Pull	9.0g	**JESD22-C100**		0/5
Bond Shear	90g	**AEC-Q100-001**		0/5
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/5
Solderability CA	Condition C steam aging (8hrs), Condition A solder Dip (215 for 5 sec)	**JESD22-B102**		0/11
Solderability CB	Condition C steam aging (8hrs), Condition B solder Dip (245 for 5 sec)	**JESD22-B102**		0/11

Qualification Plan	Device	Package	Process	No. of Lots
Q20110610	FDMC8200S	MLDEDCX8	PT7 N	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	**JESD22-A113**		0/154
MSL1	260C, 3 cycles	**J-STD_020**		0/22
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	**JESD22-A110**	96 hrs	0/77
Temperature Cycle	-65C, 150C	**JESD22-A104**	500 cycles	0/77
Bond Pull	9.0g	**JESD22-C100**		0/5
Bond Shear	90g	**AEC-Q100-001**		0/5
Die Shear	0.4g/mil sq	**MIL-STD-883-2019**		0/5
Solderability CA	Condition C steam aging (8hrs), Condition A solder Dip (215 for 5 sec)	**JESD22-B102**		0/11
Solderability CB	Condition C steam aging (8hrs), Condition B solder Dip (245 for 5 sec)	**JESD22-B102**		0/11